

INTERNATIONAL STANDARD

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**Field device integration (FDI) –
Part 103-4: Profiles – PROFINET**

**Intégration des appareils de terrain (FDI) –
Partie 103-4: Profils – PROFINET**



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IEC Central Office
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
Fax: +41 22 919 03 00
info@iec.ch
www.iec.ch

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International Standard IEC 62769-103-4 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

The text of this standard is based on the following documents:

CDV	Report on voting
65E/355/CDV	65E/418/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

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- a) method for the supplying and installation of device-specific functionalities, see Patent Family DE10357276;
- b) method and device for accessing a functional module of automation system, see Patent Family EP2182418;
- c) methods and apparatus to reduce memory requirements for process control system software applications, see Patent Family US2013232186;
- d) extensible device object model, see Patent Family US12/893,680;

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FIELD DEVICE INTEGRATION (FDI) –

Part 103-4: Profiles – PROFINET

1 Scope

This part of IEC 62769 specifies an FDI profile of IEC 62769 for IEC 61784-2_CP 3/4, IEC 61784-2_CP3/5 and IEC 61784-2_CP3/6 (PROFINET¹).

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61158-5-10, *Industrial communication networks – Fieldbus specifications – Part 5-10: Application layer service definition – Type 10 elements*

IEC 61784-2, *Industrial communication networks – Profiles – Part 2: Additional fieldbus profiles for real-time networks based on ISO/IEC 8802-3*

IEC 61804 (all parts), *Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

IEC 62541-100:2015, *OPC Unified Architecture – Part 100: OPC UA for Devices*

IEC 62769-2, *Field Device Integration (FDI) – Part 2: FDI Client*

NOTE 1 IEC 62769-2 is technically identical to FDI-2022.

IEC 62769-4, *Field Device Integration (FDI) – Part 4: FDI Packages*

NOTE 2 IEC 62769-4 is technically identical to FDI-2024.

IEC 62769-5, *Field Device Integration (FDI) – Part 5: FDI Information Model*

NOTE 3 IEC 62769-5 is technically identical to FDI-2025.

IEC 62769-6, *Field Device Integration (FDI) – Part 6: FDI Technology Mapping*

NOTE 4 IEC 62769-6 is technically identical to FDI-2026.

IEC 62769-7, *Field Device Integration (FDI) – Part 7: FDI Communication Devices*

NOTE 5 IEC 62769-7 is technically identical to FDI-2027.

PI Order No.: 2.122:2008, *Specification for PROFIBUS – Device Description and Device Integration – Volume 1: GSD, V5.1, July 2008: GSD*; available at <www.PROFIBUS.com>

¹ PROFINET is the trade name of the non-profit consortium PROFIBUS & PROFINET International. This information is given for the convenience of users of this technical report and does not constitute an endorsement by IEC of the trademark holder or any of its products. Compliance does not require use of the trade name. Use of the trade name requires permission of the trade name holder.

PI Order No.: 2.352:2014, *GSDML Specification for PROFINET IO*; available at www.PROFIBUS.com

3 Terms, definitions, abbreviated terms and acronyms

3.1 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 61158-5-10, IEC 61784-2, IEC 61804, IEC 62541-100, IEC 62769-2, IEC 62769-4, IEC 62769-5, IEC 62769-6, IEC 62769-7 and PI Order No.: 2.352:2014 apply.

3.2 Abbreviated terms and acronyms

For the purposes of this document, the following abbreviated terms and acronyms apply:

DCP	Discovery and basic configuration protocol (according to IEC 61158-5-10)
DNS	Domain name system
EDD	Electronic Device Description
EDDL	Electronic Device Description Language (see IEC 61804)
GSD	General station description (see PI Order No.: 2.122:2008)
GSDML	GSD markup language (see PI Order No.: 2.352:2014)
IP	Internet protocol (RFC 791)
UIP	User Interface plug-in
UUID	Universal unique identifier (see ISO/IEC 11578)
XML	Extensible markup language (see REC-xml-20081126)

4 Conventions

4.1 EDDL syntax

This part of IEC 62769 specifies content for the EDD component that is part of FDI Communication Packages. The specification content using EDDL syntax uses the font `Courier New`. The EDDL syntax is used for method signature, variable, data structure and component declarations.

4.2 XML syntax

XML syntax examples use the font `Courier New`. The XML syntax is used to describe XML document schema.

EXAMPLE: `<xs:simpleType name="ExampleType">`

4.3 Capitalizations

The IEC 62769 series uses capitalized terms to emphasize that these terms have an FDI specific meaning.

Some of these terms using an acronym as a prefix for example

- FDI Client, or
- FDI Server.

Some of these terms are compound terms such as:

- Communication Servers, or